

**30V N-Ch Power MOSFET**
**Feature**

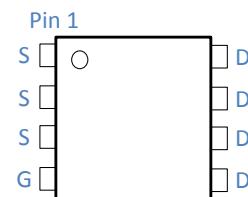
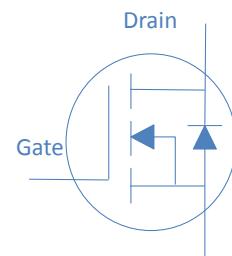
- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

$V_{DS}$	30	V
$R_{DS(on),typ}$   $V_{GS}=10V$	2.8	$m\Omega$
$I_D$ (Silicon Limited)	37	A

**Application**

- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial

Part Number	Package	Marking
HTM035N03	DFN3*3	TM035N03

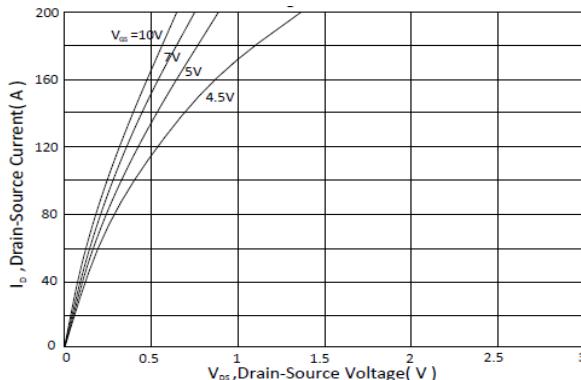
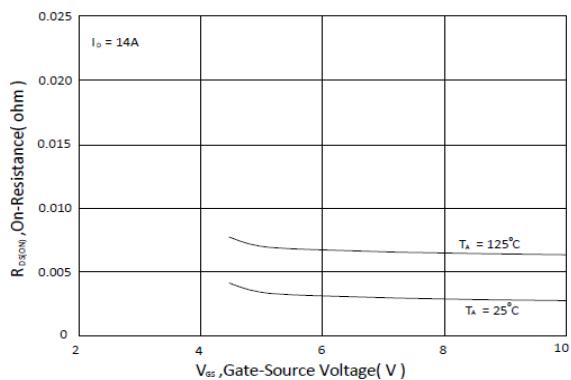
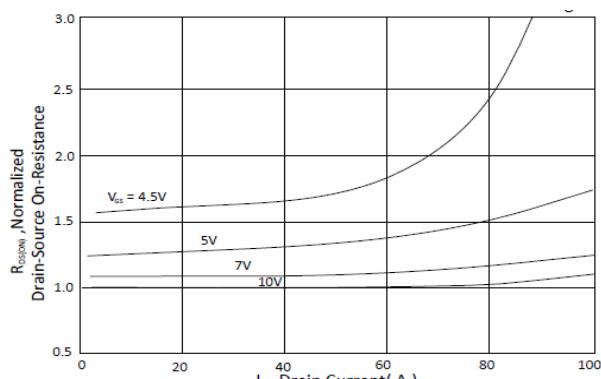
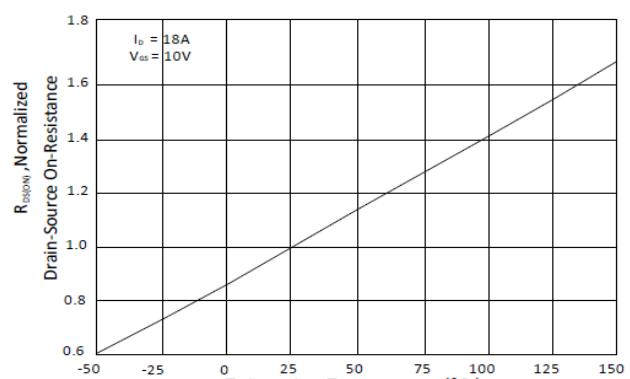
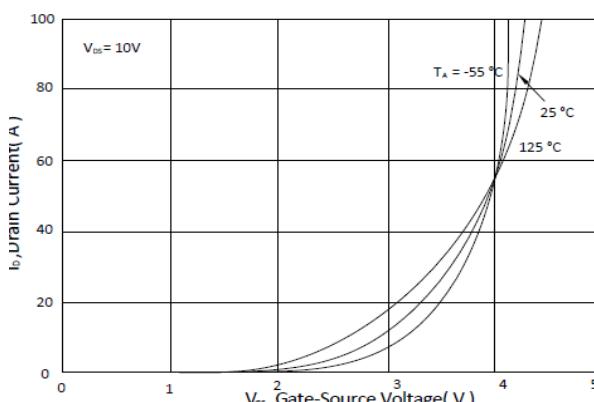
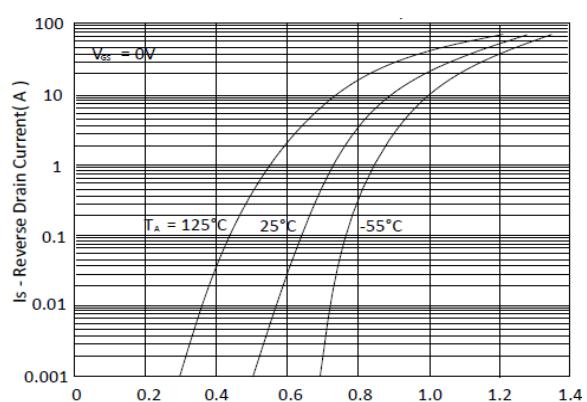

**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

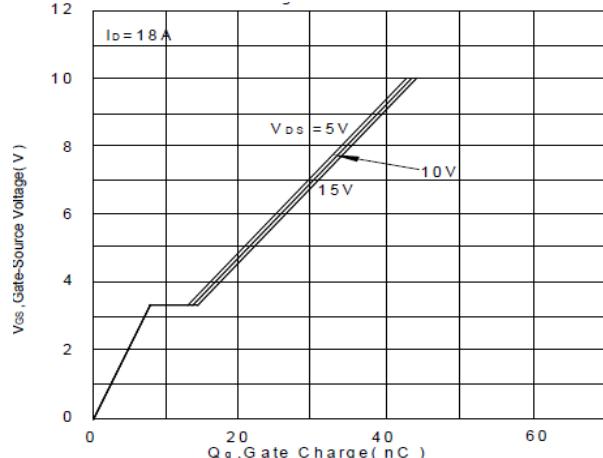
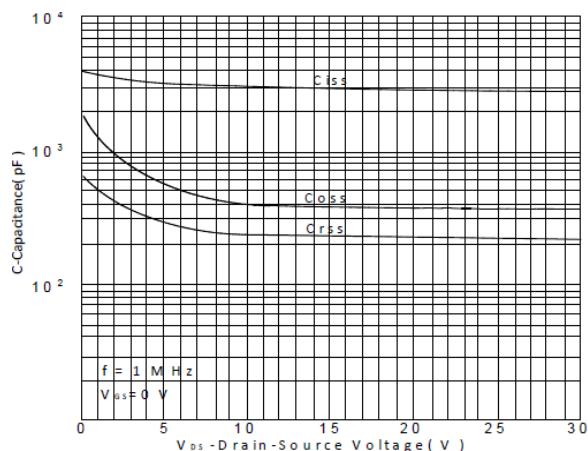
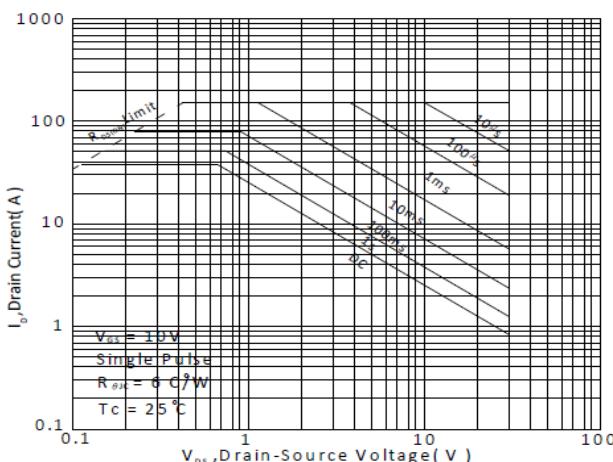
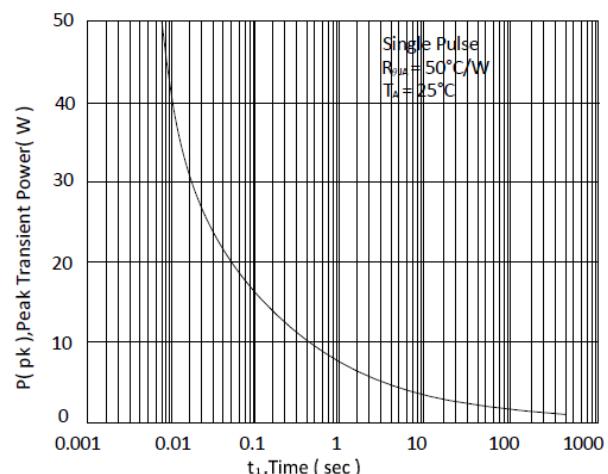
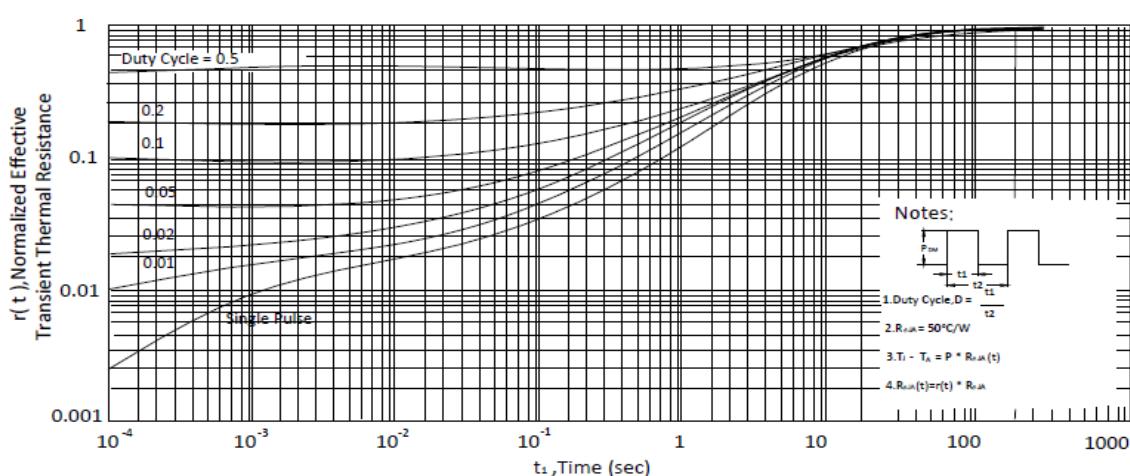
Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ C$	37	A
		$T_C=100^\circ C$	25	
Drain to Source Voltage	$V_{DS}$	-	30	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	148	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.1mH, T_C=25^\circ C$	68.4	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	2.5	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 150	°C

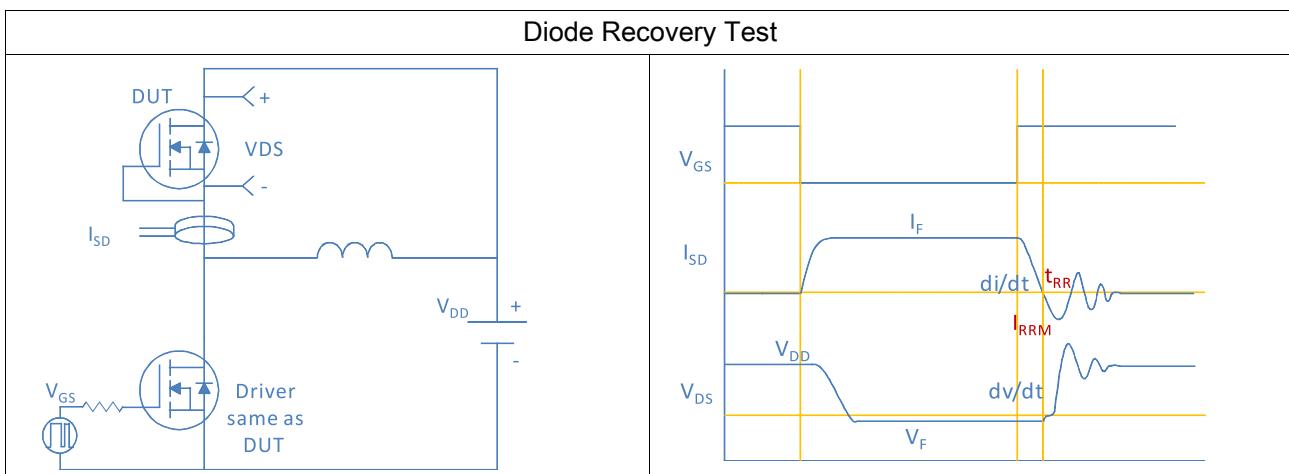
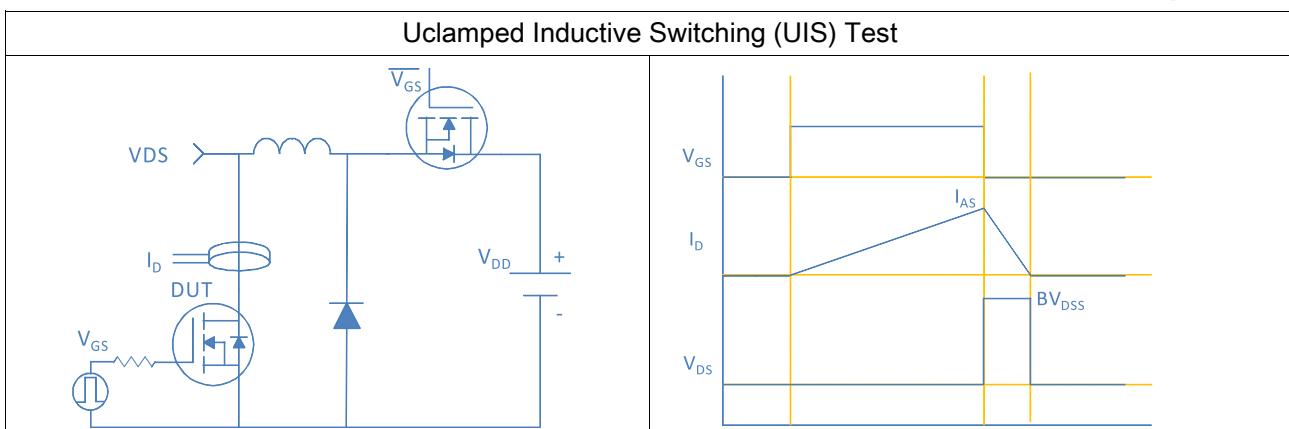
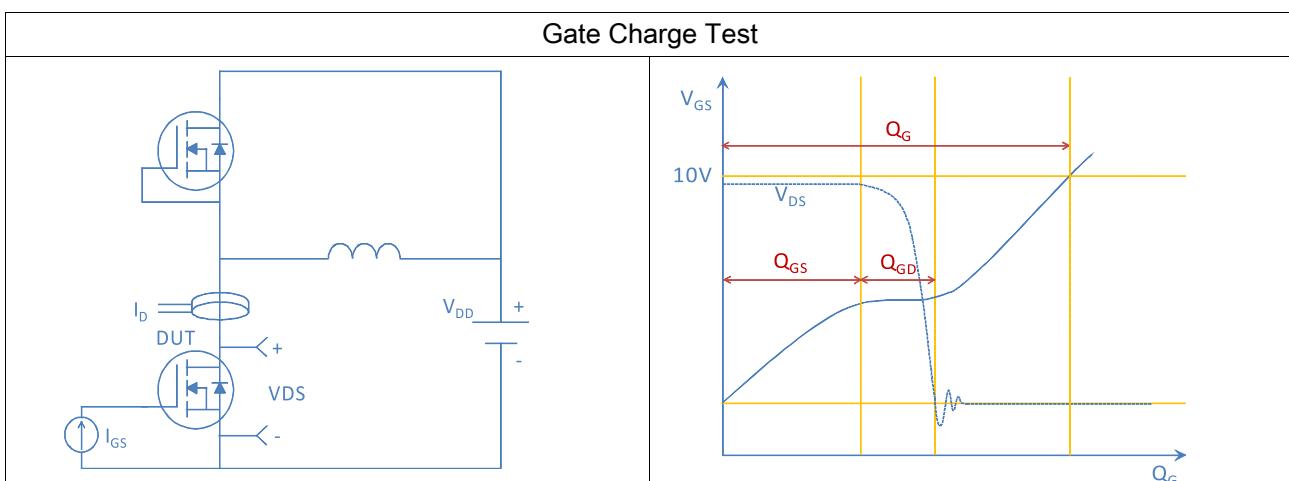
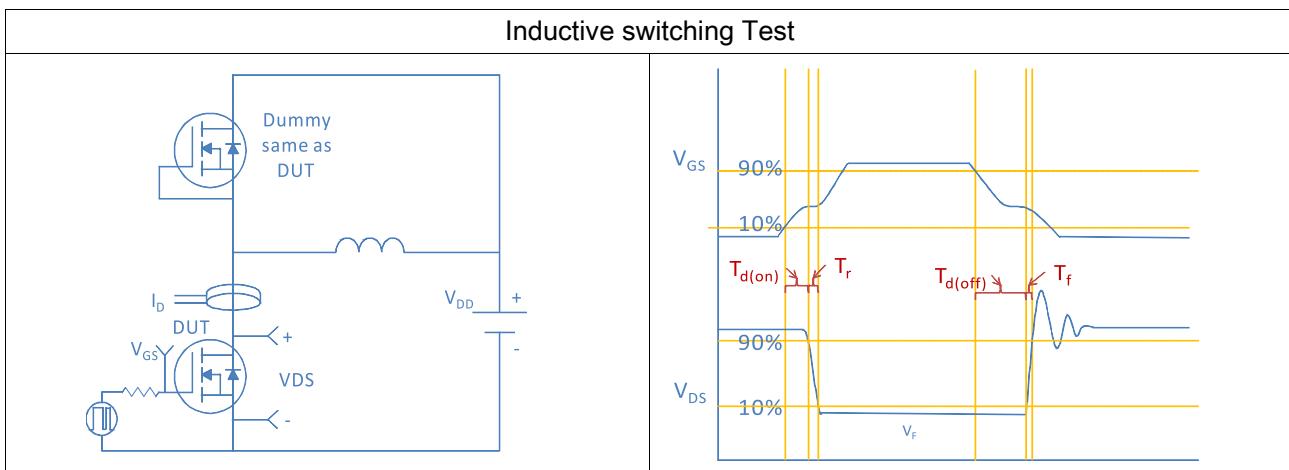
**Absolute Maximum Ratings**

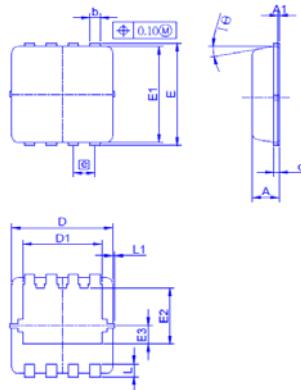
Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	50	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	6	°C/W



**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Single Pulse Maximum Power Dissipation**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient**




**Package Outline**
**DFN3\*3\_P, 8leads**

**Dimension in mm**

Dimension	A	A1	b	c	D	D1	E	E1	E2	E3	e	L	L1	θ1
Min.	0.70	0	0.24	0.10	2.95	2.25	3.15	2.95	1.65			0.30		0°
Typ.	0.80		0.30	0.152	3.00	2.35	3.20	3.00	1.75	0.575	0.65	0.40	0.13	10°
Max.	0.90	0.05	0.37	0.25	3.15	2.45	3.40	3.15	1.96			0.50		12°